


FACULTY PROFILE

Name of Teaching Staff / RMK ID	Dr.P.Balaramesh / T0556			
Designation	Associate Professor (Gr I)			
Department	Science & Humanities (Chemistry)			
Date of Joining the Institution	02.09.2008 (Regular)			
Qualifications	M.Sc	M.Phil	P.hD (Chemistry)	
Total Experience	Overall : 22.2		in RMK : 14.2	
Papers Published in Journal	Overall : 33		After Joining RMK : 33	
List of Papers Published	<ol style="list-style-type: none"> 1. Electroless Copper Deposition Using Saccharose Coating Copper Methyl Sulfonate Bath with Thiourea as Stabilizer 2. THE EFFECT OF STABILIZERS ON ELECTROLESS COPPER PLATING FROM SACCHAROSECONTAINING 3. Influence of imidazole and benzotriazole on electroless copper plating 4. bath parameters affecting electroless copper deposition 5. studies on stable metal platinum metal complexes ethylene diamine and diethanolamine 6. Influence of Thiourea or Thiocarbamate On Metal Complex and Kinetic Parameters 7. Studies on Kinetic Parameters of Thiocarbamate as Metal Complex, Complexing Agent and Stabilizer 8. Studies on Kinetic Parameters of Copper Deposits by Using XRD Technique in Electroless Deposition 9. Effects of various metal salt biodegradable compounds on electroless copper deposition 10. Effect of various salts on electroless copper methylsulfonate bath 11. Surface morphology of copper deposits by using Azide salts on various substrates electroless bath 12. Kinetic parameters of "glycine" complexing agents on electroless deposition. 13. Studies on Kinetic parameters of metal complexes 14. RECENT ADVANCES IN ELECTROLESS COPPER DEPOSITION – A REVIEW 15. Influence of azole stabilizers on various substrates electroless copper plating on various substrates 16. Influence of glycine polyquinoxaline compounds on copper plating on various substrates 17. Influence of Glycine Stabilizers on the Surface Morphology 18. Electroless plating on various substrates using various substrates 			

	<p>Mat'ial polQkQdioxQlic compo"ds</p> <ol style="list-style-type: none"> 19. St"dics o tkc l'rl"cc or Elcctfolcss Coppcí 20. A Compaíatic St"dQ or tkc S"íracc MoípkologQ or a Elcctfolcss Coppcí Kcpositio Batk "si g a Gícc a ad No-Gícc Sol:c"t 21. St"dQ or clcctfolcss coppcí aao tki rilm dpositio "si g cco-riicdlQ complcxig agc"ts 22. Role addit:cs i ccoricdlQ clcctfolcss coppcí dpositio 23. a"totcatalQtic coppcí plati g píoccss roí o co d"cti g mat'ial 24. Errcct or S"lr"í-Co"taii g Ami o Acid Stabilizcís o tkc S"íracc MoípkologQ or Eco líicdlQ Elcctfolcss Na o Coppcí Kcpositio 25. Studies on Plating Bath Requirements in Electroless Copper Deposition - A Review 26. Influence of Azole Additives on Autocatalytic Copper Thin Film Deposition 27. Electrochemical properties of mercapto additives on ecofriendly electroless copper thin film deposition 28. ELECTROLESS PLATING OF NANO CRYSTALLINE COPPER FILMS ON EPOXY LAMINATED SUBSTRATE 29. Thin film to nano copper deposition by special additives on an ecofriendly electroless bath 30. Influence of organosulphur additives on autocatalytic copper thin film deposition 31. Electroless copper deposition using 3 mercapto propionic acid as an additive 32. Stabilizing effects of mercapto additives on Eco friendly autocatalytic copper nano film deposition 33. Structural Properties of Mercapto Stabilizers on an Autocatalytic Pure Copper Metal Deposition 	
Papers Presented in Conferences (Scopus / WoS indexed only)	Overall : 5	After Joining RMK :5
Ph.Ds / Projects Guided	Ph.Ds Guided :	Student Projects Guided :
Books Published :	Count : List :	
Patents	Published Count : 1	Granted Count :
	List : Biomaterial infused chitosan beads for the effective removal of oil and heavy metal ions from industrial effluents	

Professional Memberships	Count :
	List : 1. Indian Chemical Society, 2. Member of Indian Society for Technical Education., 3. international association of Engineers. 4. Hong Kong Chemical, Biological & Environmental Engineering Society.
Consultancy Projects Completed	Count :
Awards Received	Count :
	List :
Research grants Received	
Orchid Link / ID	http://www.orcid.org/0000-0002-9153-175X ID : 0000-0002-9153-175X
Google Scholar Link / ID	http://scholar.google.co.in/citations?user=egMc3OIAAAAJ ID : egMc3OIAAAAJ
Vidwan Link / ID	https://vidwan.inflibnet.ac.in/profile/281600 ID : 281600
Research Gate Link / ID	http://www.researcherid.com/rid/AAZ-4594-2021 ID: AAZ-4594-2021
Scopus Link / ID	http://www.scopus.com/authid/detail.url?authorId=56292153500 ID : 56292153500